

3.3 V/5 V ECL Dual Differential 2:1 Multiplexer

MC10EP56, MC100EP56

Description

The MC10/100EP56 is a dual, fully differential 2:1 multiplexer. The differential data path makes the device ideal for multiplexing low skew clock or other skew sensitive signals. Multiple V_{BB} pins are provided.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The device features both individual and common select inputs to address both data path and random logic applications.

The 100 Series contains temperature compensation.

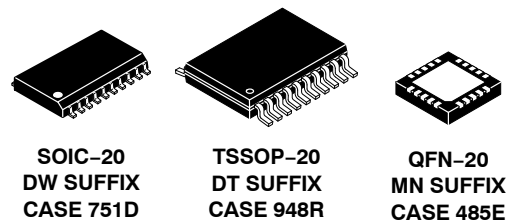
Features

- 360 ps Typical Propagation Delays
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range: $V_{CC} = 3.0$ V to 5.5 V with $V_{EE} = 0$ V
- NECL Mode Operating Range: $V_{CC} = 0$ V with $V_{EE} = -3.0$ V to -5.5 V
- Open Input Default State
- Safety Clamp on Inputs
- Separate and Common Select
- Q Output Will Default LOW with Inputs Open or at V_{EE}
- V_{BB} Outputs
- These Devices are Pb-Free and are RoHS Compliant



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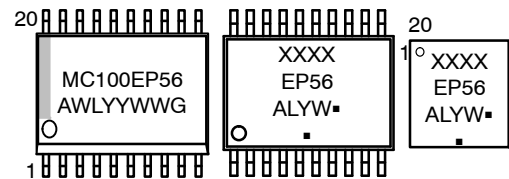


SOIC-20
DW SUFFIX
CASE 751D

TSSOP-20
DT SUFFIX
CASE 948R

QFN-20
MN SUFFIX
CASE 485E

MARKING DIAGRAMS*



XXXX = MC10 or 100
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G, ■ = Pb-Free Package

(Note: Microdot may be in either location)

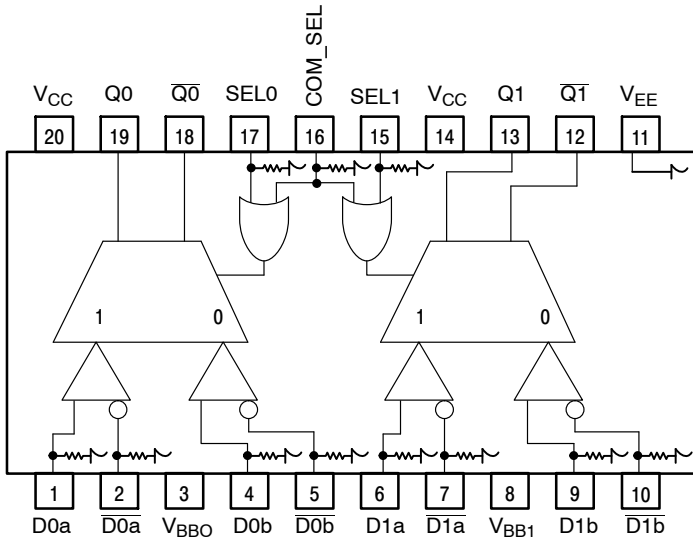
*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

| Device | Package | Shipping† |
|----------------|--------------------|--------------------|
| MC10EP56DTG | TSSOP-20 (Pb-Free) | 75 Units / Tube |
| MC10EP56DTR2G | TSSOP-20 (Pb-Free) | 2500 / Tape & Reel |
| MC10EP56MNG | QFN-20 (Pb-Free) | 92 Units / Tube |
| MC100EP56DWG | SOIC-20 (Pb-Free) | 38 Units / Tube |
| MC100EP56DTG | TSSOP-20 (Pb-Free) | 75 Units / Tube |
| MC100EP56DTR2G | TSSOP-20 (Pb-Free) | 2500 / Tape & Reel |
| MC100EP56MNG | QFN-20 (Pb-Free) | 92 Units / Tube |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. 20-Lead Package (Top View) and Logic Diagram

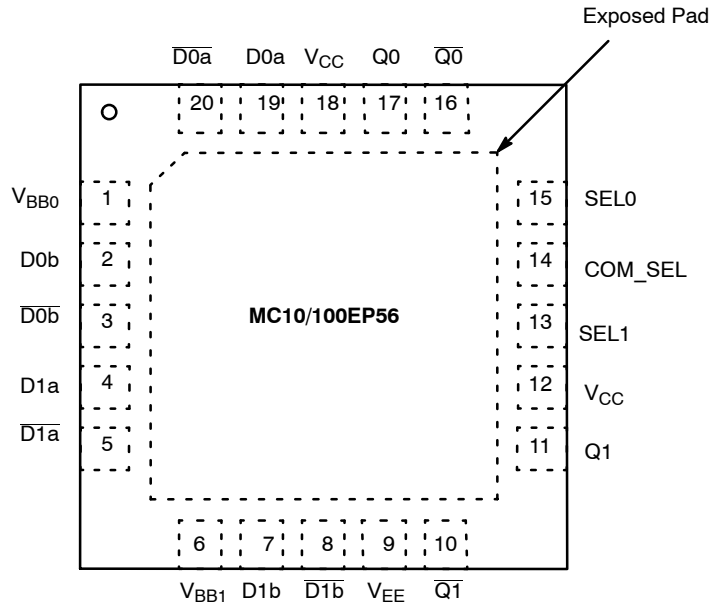
Table 1. PIN DESCRIPTION

| PIN | FUNCTION |
|---------------------------------------|--------------------------|
| $D0a^* - D1a^*$ | ECL Input Data a |
| $\overline{D0a^*} - \overline{D1a^*}$ | ECL Input Data a Invert |
| $D0b^* - D1b^*$ | ECL Input Data b |
| $\overline{D0b^*} - \overline{D1b^*}$ | ECL Input Data b Invert |
| $SEL0^* - SEL1^*$ | ECL Indiv. Select Input |
| COM_SEL^* | ECL Common Select Input |
| V_{BB0}, V_{BB1} | Output Reference Voltage |
| $Q0 - Q1$ | ECL True Outputs |
| $\overline{Q0} - \overline{Q1}$ | ECL Inverted Outputs |
| V_{CC} | Positive Supply |
| V_{EE} | Negative Supply |
| EP | Exposed Pad |

* Pins will default LOW when left open.

Table 2. TRUTH TABLE

| SEL0 | SEL1 | COM_SEL | $Q0, \overline{Q0}$ | $Q1, \overline{Q1}$ |
|------|------|---------|---------------------|---------------------|
| X | X | H | a | a |
| L | L | L | b | b |
| L | H | L | b | a |
| H | H | L | a | a |
| H | L | L | a | b |



NOTE: The Exposed Pad (EP) on package bottom must be attached to a heat-sinking conduit. The Exposed Pad may only be electrically connected to V_{EE} .

Figure 1. QFN-20 Pinout (Top View)

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Table 3. ATTRIBUTES

| Characteristics | Value |
|---|-------------------------------|
| Internal Input Pulldown Resistor | 75 kΩ |
| Internal Input Pullup Resistor | N/A |
| ESD Protection Human Body Model Machine Model Charged Device Model | > 2 kV > 150 V > 2 kV |
| Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1) | Pb-Free Pkg |
| SOIC TSSOP QFN | Level 3 Level 3 Level 1 |
| Flammability Rating Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in |
| Transistor Count | 140 Devices |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test | |

1. For additional information, see Application Note [AND8003/D](#).

Table 4. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Unit |
|---------------|--|-----------------------|---------------------|-------------|------|
| V_{CC} | PECL Mode Power Supply | $V_{EE} = 0\text{ V}$ | | 6 | V |
| V_{EE} | NECL Mode Power Supply | $V_{CC} = 0\text{ V}$ | | -6 | V |
| V_I | PECL Mode Input Voltage | $V_{EE} = 0\text{ V}$ | $V_I \leq V_{CC}$ | 6 | V |
| | NECL Mode Input Voltage | $V_{CC} = 0\text{ V}$ | $V_I \geq V_{EE}$ | -6 | V |
| I_{out} | Output Current | Continuous Surge | | 50 | mA |
| | | | | 100 | mA |
| I_{BB} | V_{BB} Sink/Source | | | ± 0.5 | mA |
| T_A | Operating Temperature Range | | | -40 to +85 | °C |
| T_{stg} | Storage Temperature Range | | | -65 to +150 | °C |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) | 0 lfpm | 20 TSSOP | 140 | °C/W |
| | | 500 lfpm | 20 TSSOP | 100 | °C/W |
| θ_{JC} | Thermal Resistance (Junction-to-Case) | Standard Board | 20 TSSOP | 23 to 41 | °C/W |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | 20 SOIC | 90 | °C/W |
| | | | 20 SOIC | 60 | °C/W |
| θ_{JC} | Thermal Resistance (Junction-to-Case) | Standard Board | 20 SOIC | 33 to 35 | °C/W |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | QFN-20 | 47 | °C/W |
| | | | QFN-20 | 33 | °C/W |
| θ_{JC} | Thermal Resistance (Junction-to-Case) | Standard Board | QFN-20 | 18 | °C/W |
| T_{sol} | Wave Solder | Pb-Free | <2 to 3 sec @ 260°C | 265 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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Table 5. 10EP DC CHARACTERISTICS, PECL $V_{CC} = 3.3\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 2)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-------------|--|-------|------|------|------|------|------|------|------|------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Power Supply Current | 45 | 61 | 75 | 45 | 63 | 75 | 45 | 65 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 3) | 2165 | 2290 | 2415 | 2230 | 2355 | 2480 | 2290 | 2415 | 2540 | mV |
| V_{OL} | Output LOW Voltage (Note 3) | 1365 | 1490 | 1615 | 1430 | 1555 | 1680 | 1490 | 1615 | 1740 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) | 2090 | | 2415 | 2155 | | 2480 | 2215 | | 2540 | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) | 1365 | | 1690 | 1460 | | 1755 | 1490 | | 1815 | mV |
| V_{BB} | Output Voltage Reference | 1790 | 1890 | 1990 | 1855 | 1955 | 2055 | 1915 | 2015 | 2115 | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4) | 2.0 | | 3.3 | 2.0 | | 3.3 | 2.0 | | 3.3 | V |
| I_{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I_{IL} | Input LOW Current | -150 | | | -150 | | | -150 | | | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

2. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.3 V to -2.2 V.
3. All loading with 50 Ω to $V_{CC} - 2.0\text{ V}$.
4. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 6. 10EP DC CHARACTERISTICS, PECL $V_{CC} = 5.0\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 5)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-------------|--|-------|------|------|------|------|------|------|------|------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Power Supply Current | 45 | 61 | 75 | 45 | 63 | 75 | 45 | 65 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 6) | 3865 | 3990 | 4115 | 3930 | 4055 | 4180 | 3990 | 4115 | 4240 | mV |
| V_{OL} | Output LOW Voltage (Note 6) | 3065 | 3190 | 3315 | 3130 | 3255 | 3380 | 3190 | 3315 | 3440 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) | 3790 | | 4115 | 3855 | | 4180 | 3915 | | 4240 | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) | 3065 | | 3390 | 3130 | | 3455 | 3190 | | 3515 | mV |
| V_{BB} | Output Voltage Reference | 3490 | 3590 | 3690 | 3555 | 3655 | 3755 | 3615 | 3715 | 3815 | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 7) | 2.0 | | 5.0 | 2.0 | | 5.0 | 2.0 | | 5.0 | V |
| I_{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I_{IL} | Input LOW Current | -150 | | | -150 | | | -150 | | | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

5. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +2.0 V to -0.5 V.
6. All loading with 50 Ω to $V_{CC} - 2.0\text{ V}$.
7. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

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Table 7. 10EP DC CHARACTERISTICS, NECL $V_{CC} = 0\text{ V}$, $V_{EE} = -5.5\text{ V}$ to -3.0 V (Note 8)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-------------|---|--------------|-------|-------|--------------|-------|-------|--------------|-------|-------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Power Supply Current | 45 | 61 | 75 | 45 | 63 | 75 | 45 | 65 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 9) | -1135 | -1010 | -885 | -1070 | -945 | -820 | -1010 | -885 | -760 | mV |
| V_{OL} | Output LOW Voltage (Note 9) | -1935 | -1810 | -1685 | -1870 | -1745 | -1620 | -1810 | -1685 | -1560 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) | -1210 | | -885 | -1145 | | -820 | -1085 | | -760 | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) | -1935 | | -1610 | -1870 | | -1545 | -1810 | | -1485 | mV |
| V_{BB} | Output Voltage Reference | -1510 | -1410 | -1310 | -1445 | -1345 | -1245 | -1385 | -1285 | -1185 | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 10) | $V_{EE}+2.0$ | | 0.0 | $V_{EE}+2.0$ | | 0.0 | $V_{EE}+2.0$ | | 0.0 | V |
| I_{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I_{IL} | Input LOW Current | -150 | | | -150 | | | -150 | | | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

8. Input and output parameters vary 1:1 with V_{CC} .

9. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

10. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 8. 100EP DC CHARACTERISTICS, PECL $V_{CC} = 3.3\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 11)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-------------|---|-------|------|------|------|------|------|------|------|------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Power Supply Current | 50 | 61 | 75 | 50 | 63 | 77 | 55 | 66 | 80 | mA |
| V_{OH} | Output HIGH Voltage (Note 12) | 2155 | 2280 | 2405 | 2155 | 2280 | 2405 | 2155 | 2280 | 2405 | mV |
| V_{OL} | Output LOW Voltage (Note 12) | 1305 | 1480 | 1605 | 1305 | 1480 | 1605 | 1305 | 1480 | 1605 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) | 2075 | | 2420 | 2075 | | 2420 | 2075 | | 2420 | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) | 1305 | | 1675 | 1305 | | 1675 | 1305 | | 1675 | mV |
| V_{BB} | Output Voltage Reference | 1775 | 1875 | 1975 | 1775 | 1875 | 1975 | 1775 | 1875 | 1975 | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 13) | 2.0 | | 3.3 | 2.0 | | 3.3 | 2.0 | | 3.3 | V |
| I_{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I_{IL} | Input LOW Current | -150 | | | -150 | | | -150 | | | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

11. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $+0.3\text{ V}$ to -2.2 V .

12. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

13. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

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Table 9. 100EP DC CHARACTERISTICS, PECL $V_{CC} = 5.0\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 14)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-------------|---|-------|------|------|------|------|------|------|------|------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Power Supply Current | 50 | 61 | 75 | 50 | 63 | 77 | 55 | 66 | 80 | mA |
| V_{OH} | Output HIGH Voltage (Note 15) | 3855 | 3980 | 4105 | 3855 | 3980 | 4105 | 3855 | 3980 | 4105 | mV |
| V_{OL} | Output LOW Voltage (Note 15) | 3005 | 3180 | 3305 | 3005 | 3180 | 3305 | 3005 | 3180 | 3305 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) | 3775 | | 4120 | 3775 | | 4120 | 3775 | | 4120 | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) | 3005 | | 3375 | 3005 | | 3375 | 3005 | | 3375 | mV |
| V_{BB} | Output Voltage Reference | 3475 | 3575 | 3675 | 3475 | 3575 | 3675 | 3475 | 3575 | 3675 | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 16) | 2.0 | | 5.0 | 2.0 | | 5.0 | 2.0 | | 5.0 | V |
| I_{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I_{IL} | Input LOW Current | -150 | | | -150 | | | -150 | | | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

14. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +2.0 V to -0.5 V.

15. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

16. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 10. 100EP DC CHARACTERISTICS, NECL $V_{CC} = 0\text{ V}$, $V_{EE} = -5.5\text{ V}$ to -3.0 V (Note 17)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|-------------|---|--------------|-------|-------|--------------|-------|-------|--------------|-------|-------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Power Supply Current | 50 | 61 | 75 | 50 | 63 | 77 | 55 | 66 | 80 | mA |
| V_{OH} | Output HIGH Voltage (Note 18) | -1145 | -1020 | -895 | -1145 | -1020 | -895 | -1145 | -1020 | -895 | mV |
| V_{OL} | Output LOW Voltage (Note 18) | -1995 | -1820 | -1695 | -1995 | -1820 | -1695 | -1995 | -1820 | -1695 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) | -1225 | | -880 | -1225 | | -880 | -1225 | | -880 | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) | -1995 | | -1625 | -1995 | | -1625 | -1995 | | -1625 | mV |
| V_{BB} | Output Voltage Reference | -1525 | -1425 | -1325 | -1525 | -1425 | -1325 | -1525 | -1425 | -1325 | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 19) | $V_{EE}+2.0$ | | 0.0 | $V_{EE}+2.0$ | | 0.0 | $V_{EE}+2.0$ | | 0.0 | V |
| I_{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μA |
| I_{IL} | Input LOW Current | -150 | | | -150 | | | -150 | | | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

17. Input and output parameters vary 1:1 with V_{CC} .

18. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

19. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

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Table 11. AC CHARACTERISTICS $V_{CC} = 0\text{ V}$; $V_{EE} = -3.0\text{ V to } -5.5\text{ V}$ or $V_{CC} = 3.0\text{ V to } 5.5\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 20)

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit | | |
|--------------------------|--|-------|--------------|------|------|-----|------|------|-----|------|------|-----|----|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | | | |
| f_{max} | Maximum Frequency (See Figure 2 $F_{max}/JITTER$) | | > 3 | | | > 3 | | | > 3 | | GHz | | |
| t_{PLH} , t_{PHL} | Propagation Delay to Output Differential D to Q, \bar{Q} SEL to Q, \bar{Q} COM_SEL to Q, \bar{Q} | | | | | | | | | | ps | | |
| | | 250 | 340 | 450 | 270 | 360 | 470 | 300 | 400 | 500 | | | |
| | | 250 | 340 | 450 | 270 | 340 | 470 | 300 | 400 | 500 | | | |
| | | 250 | 350 | 450 | 270 | 360 | 470 | 300 | 400 | 500 | | | |
| t_{SKEW} | Within-Device Skew (Note 21) Device to Device Skew | | 50 | 100 | | 50 | 100 | | 50 | 100 | ps | | |
| | | | | 200 | | | 200 | | | 200 | | | |
| t_{JITTER} | Random Clock Jitter (See Figure 2 $F_{max}/JITTER$) | | 0.2 | < 1 | | 0.2 | < 1 | | 0.2 | < 1 | ps | | |
| V_{PP} | Input Voltage Swing (Differential Configuration) | 150 | 800 | 1200 | 150 | 800 | 1200 | 150 | 800 | 1200 | mV | | |
| t_r , t_f | Output Rise/Fall Times (20% - 80%) | | Q, \bar{Q} | 70 | 120 | 170 | 80 | 130 | 180 | 100 | 150 | 230 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

20. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to $V_{CC} - 2.0\text{ V}$.

21. Skew is measured between outputs under identical transitions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.

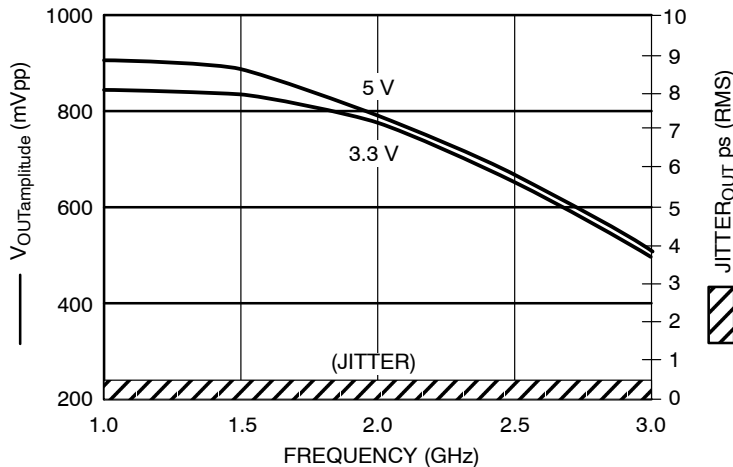


Figure 2. $F_{max}/Jitter$ @ 25°C

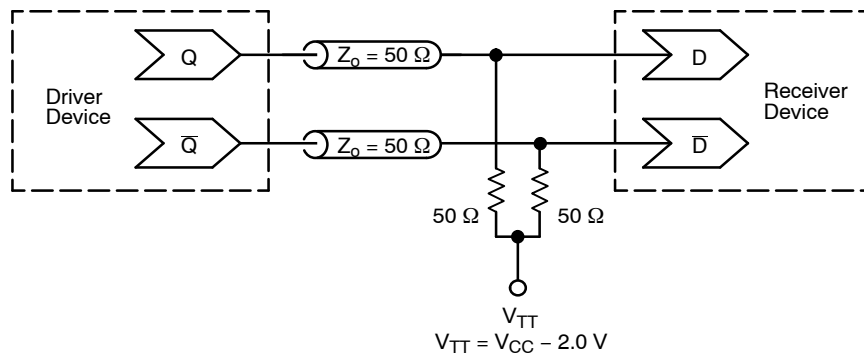


Figure 3. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) - Termination of ECL Logic Devices.)

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Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

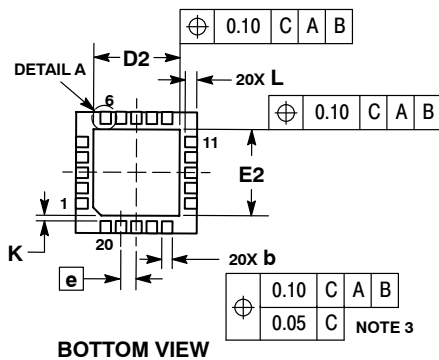
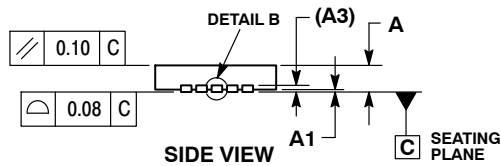
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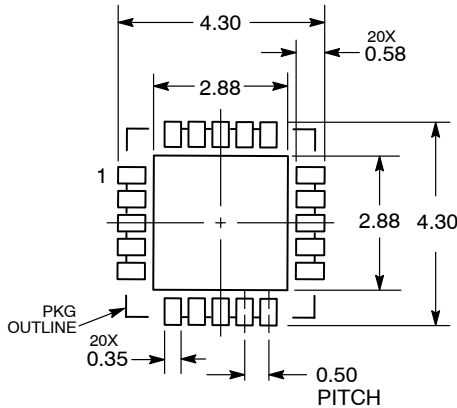
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QFN20, 4x4, 0.5P
CASE 485E
ISSUE C

DATE 13 FEB 2018

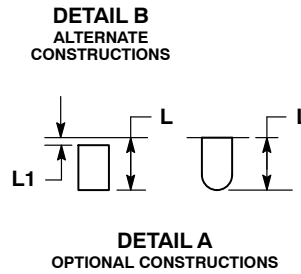
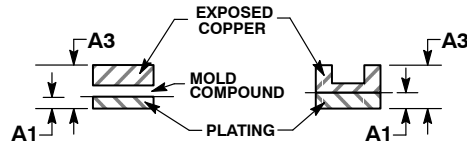


SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

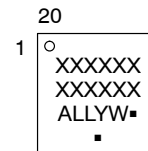


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS | | |
|-------------|----------|------|
| DIM | MIN | MAX |
| A | 0.80 | 1.00 |
| A1 | --- | 0.05 |
| A3 | 0.20 | REF |
| b | 0.20 | 0.30 |
| D | 4.00 BSC | |
| D2 | 2.60 | 2.90 |
| E | 4.00 BSC | |
| E2 | 2.60 | 2.90 |
| e | 0.50 BSC | |
| K | 0.20 REF | |
| L | 0.35 | 0.45 |
| L1 | 0.00 | 0.15 |

GENERIC MARKING DIAGRAM*



- XXXXXX= Specific Device Code
- A = Assembly Location
- LL = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

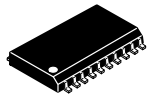
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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| DESCRIPTION: | QFN20, 4X4, 0.5P | PAGE 1 OF 1 |

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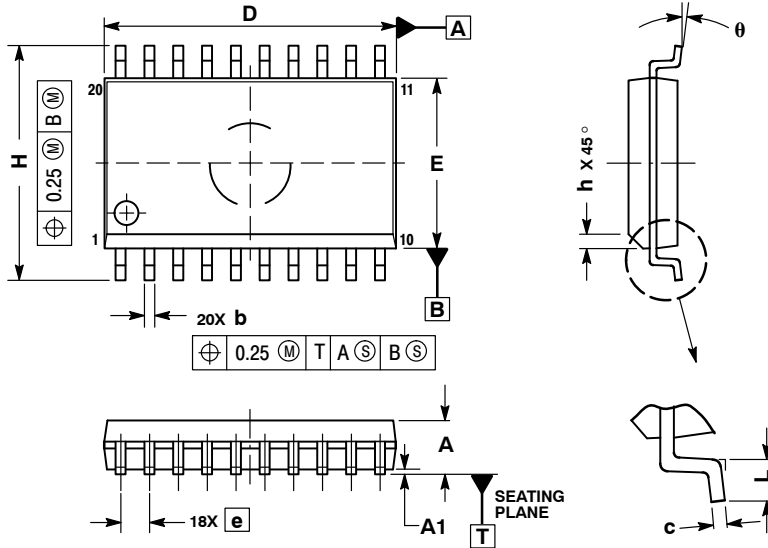
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-20 WB
CASE 751D-05
ISSUE H

DATE 22 APR 2015

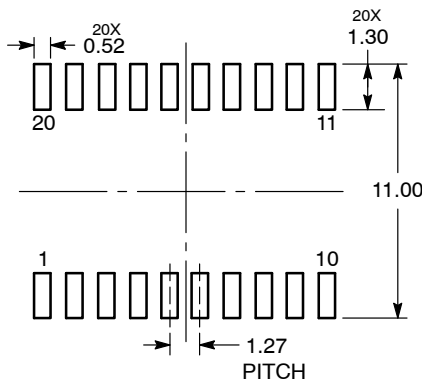


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS | |
|-----|-------------|-------|
| | MIN | MAX |
| A | 2.35 | 2.65 |
| A1 | 0.10 | 0.25 |
| b | 0.35 | 0.49 |
| c | 0.23 | 0.32 |
| D | 12.65 | 12.95 |
| E | 7.40 | 7.60 |
| e | 1.27 BSC | |
| H | 10.05 | 10.55 |
| h | 0.25 | 0.75 |
| L | 0.50 | 0.90 |
| θ | 0° | 7° |

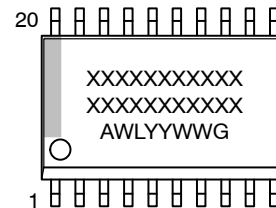
RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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| DESCRIPTION: | SOIC-20 WB | PAGE 1 OF 1 |

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

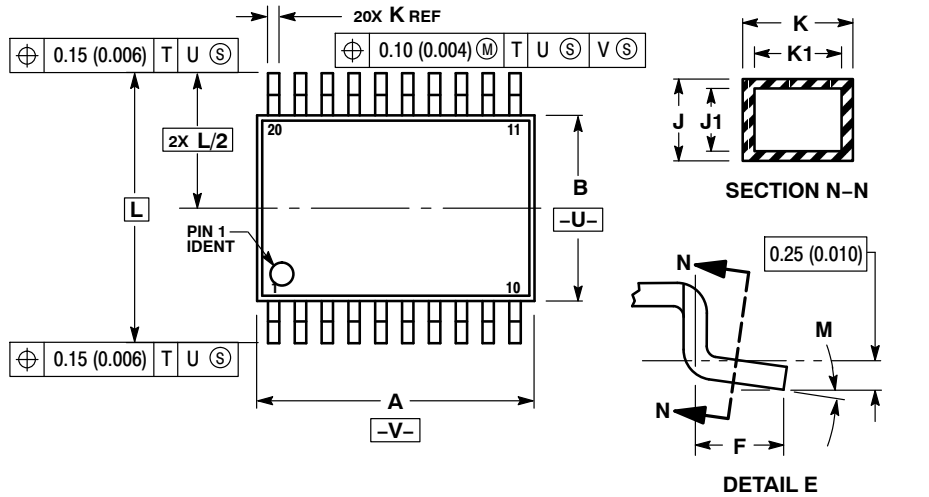
ON Semiconductor®



TSSOP-20 WB
CASE 948E
ISSUE D

DATE 17 FEB 2016

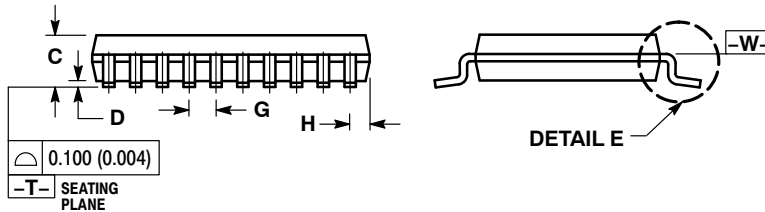
SCALE 2:1



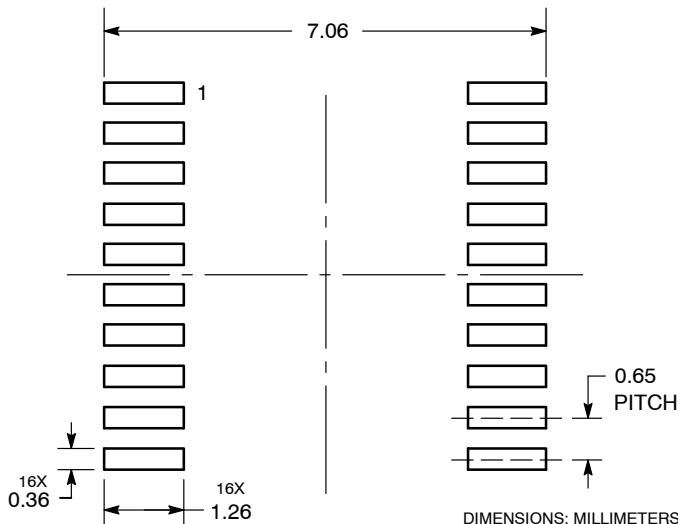
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

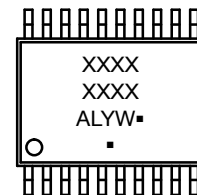
| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 6.40 | 6.60 | 0.252 | 0.260 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.27 | 0.37 | 0.011 | 0.015 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |



SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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| DESCRIPTION: | TSSOP-20 WB | PAGE 1 OF 1 |

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